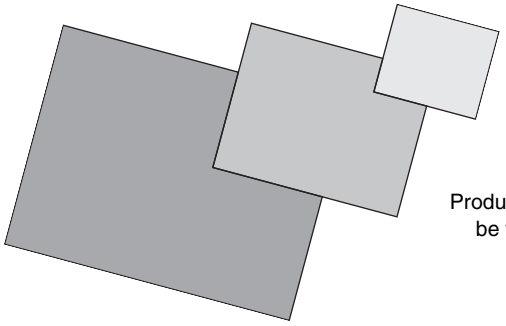
Metalized Plates



Product may not be to scale

Vishay Electro-Films (EFI) offers the widest variety of metalization options, substrate materials, surface finishes and through hole metalization with rapid high volume delivery.

FEATURES

- Metalization on 1, 2, or 6 surfaces
- Excellent adhesion to all materials
- Sizes to 4 inches x 4 inches
- Metalized through holes with excellent adhesion
- Polished or “As Fired” surfaces
- High volume
- Rapid delivery

Unique, proprietary sputtering systems provide high volume and uniform deposition for up to three different metalization layers on one or both sides without breaking vacuum. This insures excellent adhesion to the surfaces and on the metalized thru-hole walls.

Volume plating with the conditions precisely controlled for each substrate insures uniform plating thickness from substrate to substrate as well as across individual substrates.

SUBSTRATE MATERIALS

Alumina, 99.6 %

- Thickness - 0.010 inches, 0.015 inches, 0.025 inches
- Surface finish - as fired, 2 - 4 microinches Polished, < 2 microinches
- Loss factor: 0.0004 typical at 25 °C - 1 MHz
- Dielectric constant: 9.8 typical at 25 °C - 10 GHz

Beryllium Oxide, Aluminum Nitride

- For high thermal conductivity requirements
- Metalized, patterned, with resistors

Quartz

- For low dielectric constant applications
- Very low noise amplifiers
- Consistently high adhesion levels

METALIZATION

The Vishay EFI sputtering systems employ long life (15 year), large area targets that provide consistent resistance, TCR and long term stability characteristics from plate-to-plate and run-to-run. You can be sure that all parts shipped for decades will have the same characteristics as the qualification run.

- Sputtered resistance material, 10 Ω/square to 200 Ω/square
- High stability nichrome.
- Moisture resistant tantalum nitride.
- Sputtered adhesion or barrier metal layers: NiCr, Ti, TiW, Ta2N, Mo, Cu, Ni, Pd.
- Plated layers to 1000 microinches: Ni, Cu, Au.

Ordering Information; Consult Application Engineer

Disclaimer

All product specifications and data are subject to change without notice.

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